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(57) **ABSTRACT**

A heat dissipation module and a dynamic random access memory device are provided. The heat dissipation module includes a main body, a fan, and an electrical connection component. The main body is fixedly disposed on a substrate of a memory component that includes a dynamic random access memory. The main body includes a receiving through-hole, a plurality of guide through-holes, and a plurality of exhaust through-holes. The fan is fixedly disposed on the main body and configured to allow air outside the substrate to enter the substrate through the receiving through-hole and the guide through-holes, and the air entering the substrate through the receiving through-hole and the guide through-holes is discharged outwardly through the exhaust through-holes. The electrical connection component is configured for an external power supply module to supply power to the fan.

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